WHAT IS CLAIMED IS:

1	1.	An optocoupler package comprising:	
2	(a)	a substrate comprising a leadframe and a molding compound;	
3	(b)	an optical emitter;	
4	(c)	an optical receiver, wherein the optical emitter and the optical receiver	
5	are electrically coupled to the leadframe; and		
6	(d)	an optically transmissive medium disposed between the optical emitter	
7	and optical receiver.		
1	2.	The optocoupler package of claim 1 further comprising a plurality of	
2	conductive structure	s coupled to the leadframe, wherein the conductive structures have	
3	heights greater than the heights of the optical receiver and the optical emitter.		
1	3.	The optocoupler package of claim 2 wherein the conductive structures	
2	are solder structures.		
1	4.	The optocoupler package of claim 1 further comprising bond wires	
2	electrically coupling the optical receiver to the leadframe and electrically coupling the optical		
3	emitter to the leadframe.		
1	5.	The optocoupler package of claim 1 wherein the leadframe includes a	
2	etched portions and non-etched portions, and wherein the etched portions are covered by the		
3	molding compound and the non-etched portions are not covered by the molding compound.		
1	6.	The optocoupler package of claim 1 wherein the leadframe comprises	
2	copper.		
1	7.	The optocoupler package of claim 1 wherein a plurality of	
2	optocouplers are on the substrate.		
1	8.	The optocoupler package of claim wherein the leadframe includes a	
2	etched portions and non-etched portions at a first side, and wherein the etched portions are		
3	covered by the molding compound and the non-etched portions are not covered by the		
4	molding compound, and wherein the molding compound completely covers the second side		
5	of the leadframe.		

1	9.	A method for forming an optocoupler package comprising:	
2	(a)	forming a substrate comprising a leadframe and a molding compound;	
3	(b)	attaching an optical emitter and an optical receiver to the substrate; and	
4	(c)	depositing a light transmissive material between the optical emitter and	
5	the optical receiver.		
1	10.	The method of claim 9 further comprising:	
2	forming a plurality of conductive structures on the substrate, wherein the		
3	conductive structures have heights greater than the heights of the optical emitter and optical		
4	receiver.		
1	11.	The method of claim 9 wherein the method comprises, prior to (a),	
2	etching the leadframe.		
1	12.	The method of claim 9 wherein the leadframe comprises copper.	
1	13.	The method of claim 9 further comprising attaching wires from the	
2	optical emitter and the optical receiver to the leadframe.		
1	14.	The method of claim 9 further comprising depositing an opaque	
2	material on the light	transmissive material.	
1	15.	The method of claim 9 further comprising attaching at least four	
2	optical emitters and at least four optical receivers on the substrate.		
1	16.	An optocoupler package comprising:	
2	(a)	a substrate; and	
3	(b)	at least two optical emitters;	
4	(c)	at least two optical receivers;	
5	(d)	optically transmissive media between adjacent optical emitters and	
6	optical receivers; and		
7	(e)	a light reflective material on the optically transmissive media,	
8	wherein the optical emitters and the optical receivers are on the substrate.		
1	17.	The optocoupler package of claim 16 wherein the substrate includes a	
2	leadframe including	etched portions	

- 1 18. The optocoupler package of claim 16 wherein the substrate comprises 2 a leadframe that includes copper and a molding compound.
- 1 19. The optocoupler package of claim 16 further comprising a chip including a MOSFET on the substrate.
- 1 20. The optocoupler package of claim 1 further comprising a chip 2 including a MOSFET on the substrate.